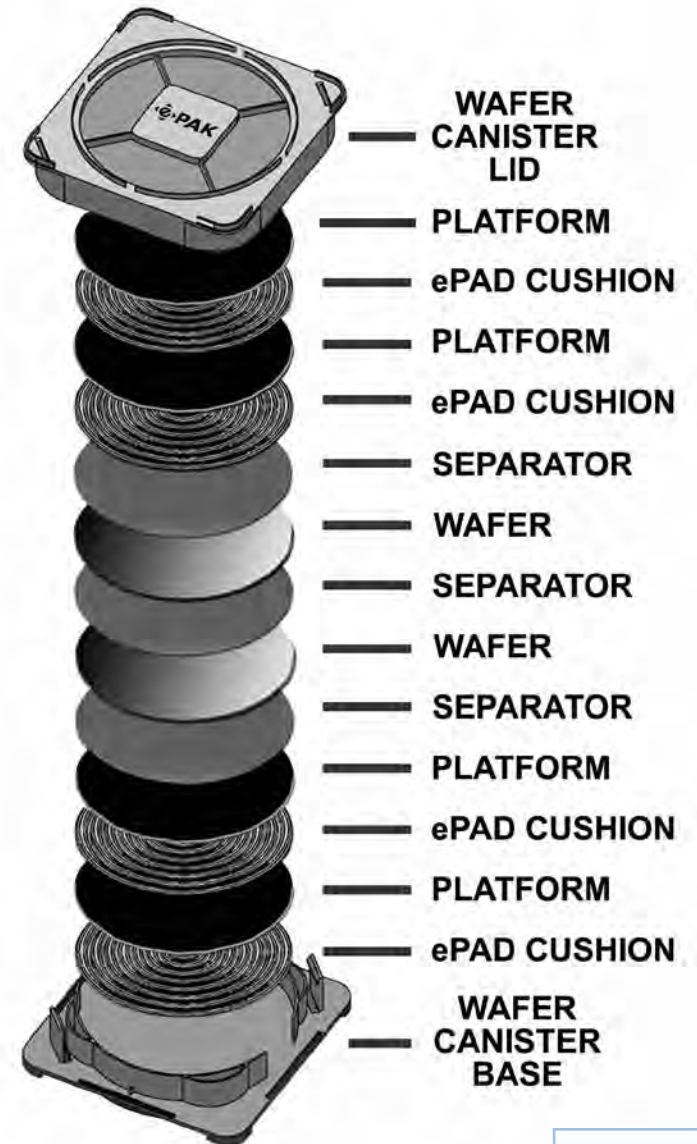


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High performance alternative to foam-based solutions

- Made from proprietary, low-ionic, flexible, conductive polystyrene
- Ideal for both Cu and Al metallized wafers
- Best choice for both long and short term storage needs
- Available for 6", 8" and 12" wafer sizes



(PATENTS: US #7425362, Singapore #105587, Japan #4205540, Taiwan #I297662, PRC#ZL 03 2 07819.6)

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